Chip Monolithic Ceramic Capacitors

muRata

Medium Voltage Low Dissipation Factor

Features

- 1. Murata's original internal electrode structure realizes high flash-over voltage.
- 2. A new monolithic structure for small, surfacemountable devices capable of operating at high voltage levels.
- 3. Sn-plated external electrodes realize good solderability.
- 4. Use the GRM21/31 type with flow or reflow soldering, and other types with reflow soldering only.
- 5. Low-loss and suitable for high frequency circuits

Applications

- Ideal for use on high frequency pulse circuits such as snubber circuits for switching power supplies, DC-DC converters, ballasts (inverter fluorescent lamps), etc.
- 2. Ideal for use as the ballast in liquid crystal back lighting inverters.
- Please contact our sales representatives or engineers before using our products for other applications not specified above.

SL/U2J Characteristics

GRM31A7U2J681JW31D

DC630

U2J (EIA)

Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance (pF)	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM21A7U2E101JW31D	DC250	U2J (EIA)	100 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E151JW31D	DC250	U2J (EIA)	150 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E221JW31D	DC250	U2J (EIA)	220 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E331JW31D	DC250	U2J (EIA)	330 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E471JW31D	DC250	U2J (EIA)	470 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E681JW31D	DC250	U2J (EIA)	680 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E102JW31D	DC250	U2J (EIA)	1000 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E152JW31D	DC250	U2J (EIA)	1500 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM21A7U2E222JW31D	DC250	U2J (EIA)	2200 ±5%	2.0	1.25	1.0	0.7	0.3 min.
GRM31A7U2E332JW31D	DC250	U2J (EIA)	3300 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2E472JW31D	DC250	U2J (EIA)	4700 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31B7U2E682JW31L	DC250	U2J (EIA)	6800 ±5%	3.2	1.6	1.25	1.5	0.3 min.
GRM31B7U2E103JW31L	DC250	U2J (EIA)	10000 ±5%	3.2	1.6	1.25	1.5	0.3 min.
GRM31A7U2J100JW31D	DC630	U2J (EIA)	10 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J150JW31D	DC630	U2J (EIA)	15 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J220JW31D	DC630	U2J (EIA)	22 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J330JW31D	DC630	U2J (EIA)	33 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J470JW31D	DC630	U2J (EIA)	47 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J680JW31D	DC630	U2J (EIA)	68 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J101JW31D	DC630	U2J (EIA)	100 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J151JW31D	DC630	U2J (EIA)	150 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J221JW31D	DC630	U2J (EIA)	220 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J331JW31D	DC630	U2J (EIA)	330 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U2J471JW31D	DC630	U2J (EIA)	470 ±5%	3.2	1.6	1.0	1.5	0.3 min.



Part Number	Dimensions (mm)							
Part Number	L	W	Т	e min.	g min.			
GRM21A	2.0 ±0.2	1.25 ±0.2	1.0 +0 0.3		0.7			
GRM31A	3.2 +0.2	1.6 +0.2	1.0 +0,-0.3					
GRM31B	3.2 ±0.2	1.6 ±0.2	1.25 +0,-0.3		1.5*			
GRM32A	3.2 +0.2	2.5 +0.2	1.0 +0,-0.3	0.3	1.5			
GRM32B	3.Z <u>1</u> 0.Z	2.5 ±0.2	1.25 +0,-0.3					
GRM42A	4.5 ±0.3	2.0 +0.2	1.0 +0,-0.3		29			
GRM42D	4.5 ±0.5	2.0 <u>1</u> 0.2	2.0 ±0.3		2.9			

* GRM31A7U3D, GRM32A7U3D, GRM32B7U3D : 1.8mm min.



3.2

1.6

1.0

680 ±5%

Continued on the following page.

1.5

0.3 min.

Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance (pF)	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode ((mm)
GRM31A7U2J102JW31D	DC630	U2J (EIA)	1000 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM32A7U2J152JW31D	DC630	U2J (EIA)	1500 ±5%	3.2	2.5	1.0	1.5	0.3 min.
GRM32A7U2J222JW31D	DC630	U2J (EIA)	2200 ±5%	3.2	2.5	1.0	1.5	0.3 min.
GRM31A7U3A100JW31D	DC1000	U2J (EIA)	10 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A150JW31D	DC1000	U2J (EIA)	15 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A220JW31D	DC1000	U2J (EIA)	22 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A330JW31D	DC1000	U2J (EIA)	33 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A470JW31D	DC1000	U2J (EIA)	47 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A680JW31D	DC1000	U2J (EIA)	68 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A101JW31D	DC1000	U2J (EIA)	100 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A151JW31D	DC1000	U2J (EIA)	150 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A221JW31D	DC1000	U2J (EIA)	220 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31A7U3A331JW31D	DC1000	U2J (EIA)	330 ±5%	3.2	1.6	1.0	1.5	0.3 min.
GRM31B7U3A471JW31L	DC1000	U2J (EIA)	470 ±5%	3.2	1.6	1.25	1.5	0.3 min.
GRM31A7U3D100JW31D	DC2000	U2J (EIA)	10 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D120JW31D	DC2000	U2J (EIA)	12 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D150JW31D	DC2000	U2J (EIA)	15 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D180JW31D	DC2000	U2J (EIA)	18 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D220JW31D	DC2000	U2J (EIA)	22 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D270JW31D	DC2000	U2J (EIA)	27 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D330JW31D	DC2000	U2J (EIA)	33 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D390JW31D	DC2000	U2J (EIA)	39 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D470JW31D	DC2000	U2J (EIA)	47 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D560JW31D	DC2000	U2J (EIA)	56 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM31A7U3D680JW31D	DC2000	U2J (EIA)	68 ±5%	3.2	1.6	1.0	1.8	0.3 min.
GRM32A7U3D820JW31D	DC2000	U2J (EIA)	82 ±5%	3.2	2.5	1.0	1.8	0.3 min.
GRM32A7U3D101JW31D	DC2000	U2J (EIA)	100 ±5%	3.2	2.5	1.0	1.8	0.3 min.
GRM32A7U3D121JW31D	DC2000	U2J (EIA)	120 ±5%	3.2	2.5	1.0	1.8	0.3 min.
GRM32A7U3D151JW31D	DC2000	U2J (EIA)	150 ±5%	3.2	2.5	1.0	1.8	0.3 min.
GRM32B7U3D181JW31L	DC2000	U2J (EIA)	180 ±5%	3.2	2.5	1.25	1.8	0.3 min.
GRM32B7U3D221JW31L	DC2000	U2J (EIA)	220 ±5%	3.2	2.5	1.25	1.8	0.3 min.
GRM42D1X3F100JY02L	DC3150	SL (JIS)	10 ±5%	4.5	2.0	2.0	2.9	0.3 min.
GRM42D1X3F120JY02L	DC3150	SL (JIS)	12 ±5%	4.5	2.0	2.0	2.9	0.3 min.
GRM42D1X3F150JY02L	DC3150	SL (JIS)	15 ±5%	4.5	2.0	2.0	2.9	0.3 min.
GRM42D1X3F180JY02L	DC3150	SL (JIS)	18 ±5%	4.5	2.0	2.0	2.9	0.3 min.
GRM42D1X3F220JY02L	DC3150	SL (JIS)	22 ±5%	4.5	2.0	2.0	2.9	0.3 min.
GRM42A7U3F270JW31L	DC3150	U2J (EIA)	27 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A7U3F330JW31L	DC3150	U2J (EIA)	33 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A7U3F390JW31L	DC3150	U2J (EIA)	39 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A7U3F470JW31L	DC3150	U2J (EIA)	47 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A7U3F560JW31L	DC3150	U2J (EIA)	56 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A7U3F680JW31L	DC3150	U2J (EIA)	68 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A7U3F820JW31L	DC3150	U2J (EIA)	82 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A7U3F101JW31L	DC3150	U2J (EIA)	100 ±5%	4.5	2.0	1.0	2.9	0.3 min.

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Application Specific Products, C0G Characteristics

Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance (pF)	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM42A5C3F050DW01L	DC3150	COG (EIA)	5.0 ±0.5pF	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F100JW01L	DC3150	COG (EIA)	10 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F120JW01L	DC3150	COG (EIA)	12 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F150JW01L	DC3150	COG (EIA)	15 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F180JW01L	DC3150	COG (EIA)	18 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F220JW01L	DC3150	COG (EIA)	22 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F270JW01L	DC3150	COG (EIA)	27 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F330JW01L	DC3150	COG (EIA)	33 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F390JW01L	DC3150	COG (EIA)	39 ±5%	4.5	2.0	1.0	2.9	0.3 min.
GRM42A5C3F470JW01L	DC3150	COG (EIA)	47 ±5%	4.5	2.0	1.0	2.9	0.3 min.

Please contact us in case that the COG char. DC3150V items are considered to use for the application which is not LCD back lighting inverters circuit.



Specifications and Test Methods

No.	Ite	em	Specifications		Test Method		
1	Operating Temperatu	ure Range	-55 to +125℃				
2	Appearar	nce	No defects or abnormalities	Visual inspection			
3	Dimensio	ns	Within the specified dimension	Using calipers			
4	Dielectric	: Strength	No defects or abnormalities		between the terminations for 1 to 5 sec., provided the discharge current is less than 50mA. Rated voltage Test voltage DC250V 200% of the rated voltage DC630V 150% of the rated voltage DC1kV, DC2kV 120% of the rated voltage DC3.15kV DC4095V		
5	Insulation F (I.R.)	Resistance	More than 10,000MΩ	The insulation resistance (DC250±25V in case of r sec. of charging.			
6	Capacita	nce	Within the specified tolerance	The capacitance/Q shoul		t 20℃ at the frequency	
7	Q		C0G/U2J char. : 1,000 min. SL char. : 400+20C*1 min.	and voltage shown as foll Capacitance C<1,000pF C≥1,000pF	Voltage AC0.5 to 5V(r.m.s.) AC1±0.2V(r.m.s.)		
8	Capacitar Temperat Character	ure	Temp. Coefficient COG char. : 0±30ppm/°C (Temp. Range : +25 to +125°C) 0+30, -72ppm/°C (Temp. Range : -55 to +25°C) U2J char. : -750±120 ppm/°C (Temp. Range : +25 to +125°C) -750+120, -347 ppm/°C (Temp. Range : -55 to +25°C) SL char. : +350 to -1000 ppm/°C (Temp. Range : +20 to +85°C)	The temperature coefficie measured in step 3 as a 1 When cycling the tempera (SL char. : +20 to +85°C, specified tolerance for th Step 1 2 3 4 5	reference. ature sequentially) the capacitance e temperature coordination 25±2 (20±2 f Min. Operatir 25±2 (20±2 f Max. Operatir	r from step 1 through 5 should be within the efficient. ture (°C) for SL char.) ng Temp.±3 for SL char.) ng Temp.±2	
9	Adhesive of Termin		No removal of the terminations or other defect should occur.	in Fig. 1 using a eutectic Then apply 10N force in t The soldering should be reflow method and should soldering is uniform and f	25±2 (20±2 for SL char.) or to the testing jig (glass epoxy board) shown utectic solder. rce in the direction of the arrow. Id be done either with an iron or using the should be conducted with care so that the n and free of defects such as heat shock. 10N, 10±1s Speed : 1.0mm/s Glass Epoxy Board		
		Appearance	No defects or abnormalities	Solder the capacitor to the	Fig. 1 e test jig (glass ep	poxy board).	
		Capacitance	Within the specified tolerance	The capacitor should be s	subjected to a sim	ple harmonic motion	
10	Vibration Resistance	Q	C0G/U2J char. : 1,000 min. SL char. : 400+20C* ¹ min.		proximate limits c to 55Hz and retu y 1 min. This mot ach 3 mutually per	of 10 and 55Hz. The Irm to 10Hz, should be ition should be applied	

*1 "C" expresses nominal capacitance value (pF).

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Specifications and Test Methods

	lte	em	Specifications		Test Method	Test Method			
11	Deflection	n	No cracking or marking defects should occur. $\begin{array}{c ccccccccccccccccccccccccccccccccccc$	in Fig. 2 using Then apply a f The soldering reflow method soldering is un	Proxy board) shown Fig. 3. iron or using the a care so that the as heat shock. m/s =1 (in mm) bl (JIS-K-8101) and ortion). Immerse in				
12	2 Solderability of Termination		75% of the terminations are to be soldered evenly and continuously.	solder solution for 2±0.5 sec. Immersing speed : 25±2.5mm/s Temp. of solder : 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu) 235±5°C H60A or H63A Eutectic Solder					
		Appearance	No marking defects	Preheat the ca	pacitor at 120 to 150℃* for 1 i	nin.			
	Desistance	Capacitance Change	Within ±2.5%	Immerse the capacitor in solder solution at 260±5°C for 10±1 se Let sit at *1room condition for 24±2 hrs., then measure. •Immersing speed : 25±2.5mm/s *Preheating for more than 3.2×2.5mm					
13	Resistance to Soldering	Q	C0G/U2J char. : 1,000 min. SL char. : 400+20C* ² min.						
	Heat	I.R.	More than 10,000MΩ			T !			
		Dielectric Strength	In accordance with item No.4	Step 1 2	Temperature 100 to 120℃ 170 to 200℃	Time 1 min. 1 min.			
		Appearance	No marking defects	Fix the capacit	or to the supporting jig (glass	epoxy board) shown			
		Capacitance Change	Within ±2.5%	 in Fig. 4 using a eutectic solder. Perform the 5 cycles according to the 4 heat treatments listed in the following table. 					
		Q	C0G char. : 1,000 min. U2J char. : 500 min.		2 hrs. at *1room condition, the				
			SL char. : $400+20C^{*2}$ min.	Step 1	Temperature (℃) Min. Operating Temp.±3	Time (min.) 30±3			
	Temperature	I.R.	More than 10,000MΩ	2	Room Temp. Max. Operating Temp.±2	2 to 3			
14	Cycle	Dielectric	In accordance with item No.4	4 Room Temp.		30±3 2 to 3			
		Strength			Glass Epoxy Board				
			No marking defects		Glass Epoxy Board				
	Humidity	Strength	No marking defects Within ±5.0%		Glass Epoxy Board Fig. 4	umidity of 90 to 95%			
15	Humidity (Steady State)	Strength Appearance Capacitance Change Q	No marking defects Within ±5.0% C0G/U2J char. : 350 min. SL char. : 275+5/2C*2 min.	for 500 ⁺²⁴ / ₀ hr Remove and l	Glass Epoxy Board Fig. 4				
15	(Steady	Strength Appearance Capacitance Change Q I.R.	No marking defects Within ±5.0% C0G/U2J char. : 350 min.	for 500 ⁺² ⁴ ₀ hr	Glass Epoxy Board Fig. 4 for sit at 40±2°C and relative h				
5	(Steady	Strength Appearance Capacitance Change Q	No marking defects Within $\pm 5.0\%$ COG/U2J char. : 350 min. SL char. : 275+5/2C* ² min. More than 1,000M Ω In accordance with item No.4	for 500 ⁺²⁴ / ₀ hr Remove and l	Glass Epoxy Board Fig. 4 for sit at 40±2°C and relative h				
15	(Steady	Strength Appearance Capacitance Change Q I.R. Dielectric Strength Appearance	No marking defects Within $\pm 5.0\%$ C0G/U2J char. : 350 min. SL char. : 275+5/2C* ² min. More than 1,000M Ω	for 500 ⁺²⁴ / ₀ hr Remove and I	Glass Epoxy Board Fig. 4 for sit at 40±2°C and relative h				
15	(Steady	Strength Appearance Capacitance Change Q I.R. Dielectric Strength	No marking defects Within $\pm 5.0\%$ COG/U2J char. : 350 min. SL char. : 275+5/2C*2 min. More than 1,000M Ω In accordance with item No.4 No marking defects Within $\pm 3.0\%$	for $500^{\pm 23}$ hr Remove and I measure.	Glass Epoxy Board Fig. 4 Fig. 4 for sit at 40±2°C and relative h s. et sit for 24±2 hrs. at *1room of the rated voltage for 1,000 ±	condition, then			
	(Steady	Strength Appearance Capacitance Change Q I.R. Dielectric Strength Appearance Capacitance	No marking defects Within $\pm 5.0\%$ COG/U2J char. : 350 min. SL char. : 275+5/2C* ² min. More than 1,000M Ω In accordance with item No.4 No marking defects	for 500 ^{±2} ⁴ hr Remove and I measure. Apply 120% o operating tem Remove and I	Glass Epoxy Board Fig. 4 Fig. 4 for sit at 40±2°C and relative h s. et sit for 24±2 hrs. at *1room of the rated voltage for 1,000 ±	2 xondition, then ⁴ 8 hrs. at maximum			
15	(Steady State)	Strength Appearance Capacitance Change Q I.R. Dielectric Strength Appearance Capacitance Change	No marking defects Within $\pm 5.0\%$ COG/U2J char. : 350 min. SL char. : 275+5/2C* ² min. More than 1,000M Ω In accordance with item No.4 No marking defects Within $\pm 3.0\%$ COG/U2J char. : 350 min.	Apply 120% o operating temp Remove and I	Glass Epoxy Board Fig. 4 Fig. 4 for sit at 40±2°C and relative h s. et sit for 24±2 hrs. at *1room of the rated voltage for 1,000 ± berature ±3°C.	andition, then			

*1 "Room condition" Temperature : 15 to 35°c, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa

*2 "C" expresses nominal capacitance value (pF).



15